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Amend  
PATENT J. Mcmillan

10/3/02  
I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to Box Non-Fee Amendment, Commissioner of Patents, Washington, DC 20231.

October 3, 2002  
Date

Ayesha S. Wilks  
10/28/02  
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TECHNOLOGY CENTER 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Vishnu K. Agarwal

Attorney Docket No.: 501082.10 (98-0616.09)

Serial No. : 09/652,714

Group Art Unit : 2815

Filed : August 31, 2000

Examiner : Jose R. Diaz

Title : DEVICE AND METHOD FOR PROTECTING AGAINST OXIDATION OF A CONDUCTIVE LAYER IN SAID DEVICE

Box Non-Fee Amendment  
Commissioner of Patents  
Washington, DC 20231

AMENDMENT

Sir:

Please amend the above-captioned patent application as follows:

In the Specification:

Please replace the paragraph beginning at page 8, line 4, with the following rewritten paragraph:

D1  
--Still other gases include diborane ( $B_2H_6$ ); phosphine ( $PH_3$ ); and carbon-silicon compounds such as methylsilane ( $CH_3SiH_3$ ) and hexamethyldisilane ( $(CH_3)_3Si-Si(CH_3)_3$ ); and hexamethyldisilazane (HMDS). Additional alternate embodiments of the current invention use hydrazine ( $N_2H_4$ ), monomethylhydrazine, carbon tetrafluoride ( $CF_4$ ),  $CHF_3$ ,  $HCl$ , and boron trichloride ( $BCl_3$ ), which are also useful in passivating dielectrics, as addressed in copending application 09/114,847, now issued as U.S. Patent No. 6,201,276 B1. Also included are mixtures of any of the gases or types of gases described above. Exemplary non-plasma process parameters using these other gases include a flow rate of about 2 sccm to about 400 sccm for